

# Wire Saw WS-22

**WS-22**, works by the lapping method, it is ideal for cutting small samples. The kerf loss ranges from 60 $\mu$ m to 80 $\mu$ m. The damage caused during cutting is very low in comparison to saws using diamond coated wires.



## **FIELDS OF USE**

- \* sample preparation in SEM and TEM
- \* fault analysis
- \* cutting single crystals
- \* use instead of spark erosion
- \* use in dental research
- \* brittle materials with cleavage planes
- \* optical windows
- \* semiconductors

## **TECHNICAL DETAILS**

- \* heavy steel base, weight app. 60 kg
- \* works like a frame saw
- \* the carrier wire consists of plane tungsten
- \* slurry feed: fully automatic
- \* oscillation freq.: settable 300 or 400/min
- \* sample tilt facility
- \* wire guiding during cut
- \* curve loss in the range of 70 to 90 $\mu$ m
- \* surface quality after cutting: as lapped

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